



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



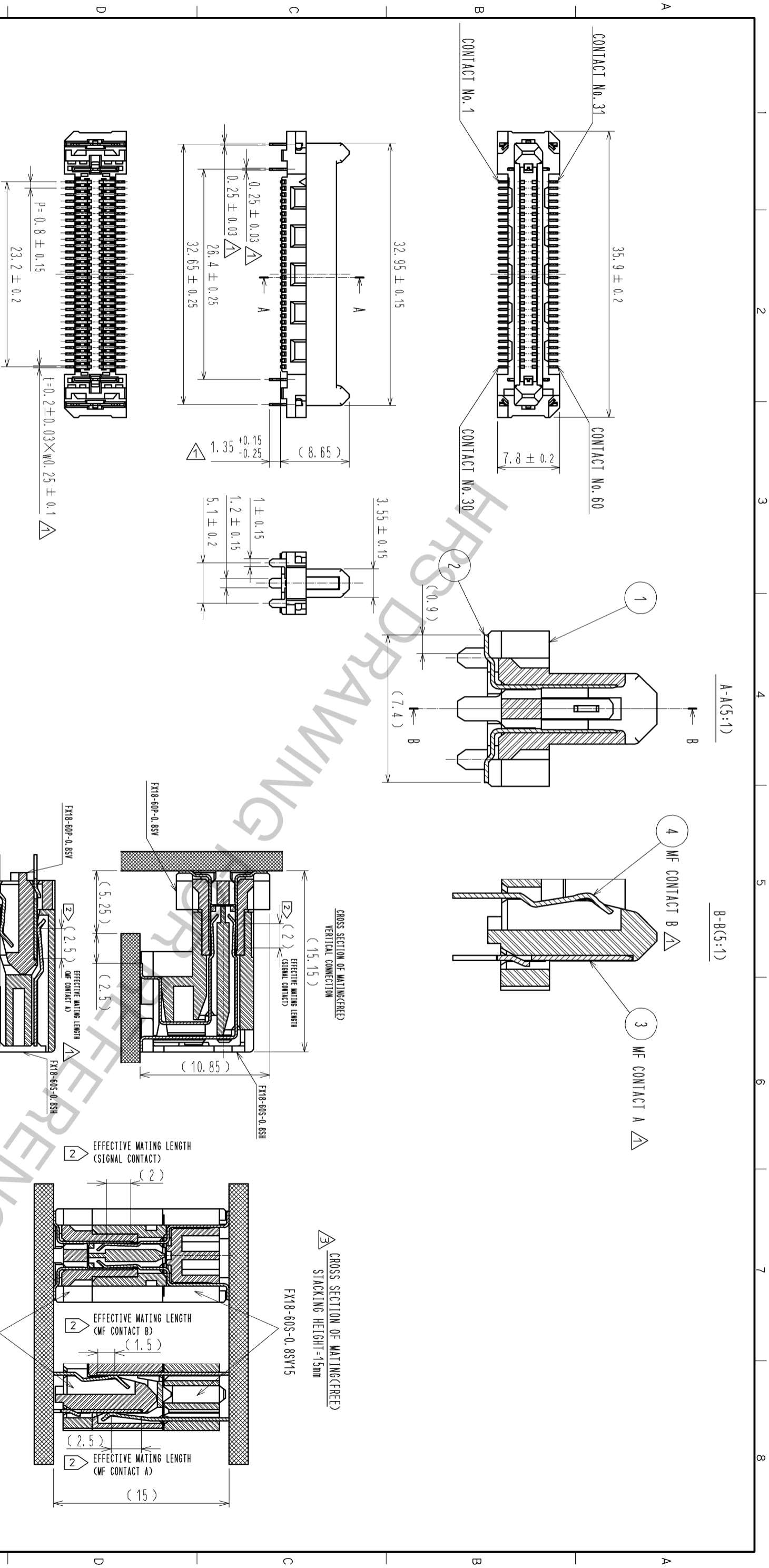
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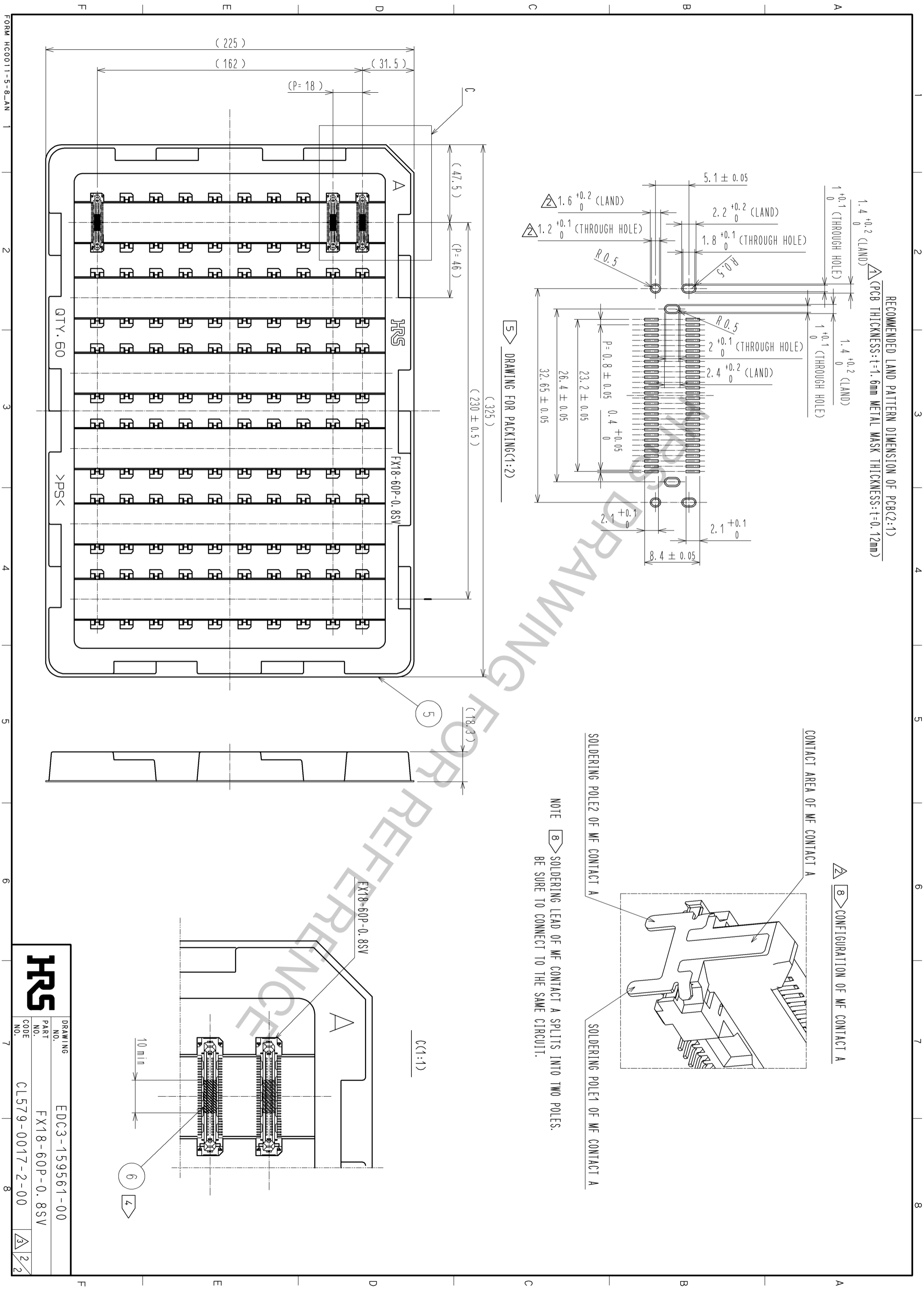


NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
 2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A->SIGNAL CONTACT->MF CONTACT B) WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
 4 IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)
 5 REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
 6 THIS IS PACKAGED IN TRAY. (60PCS/TRAY)
 7 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN'T AFFECT QUALITY LEVEL.
 8 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

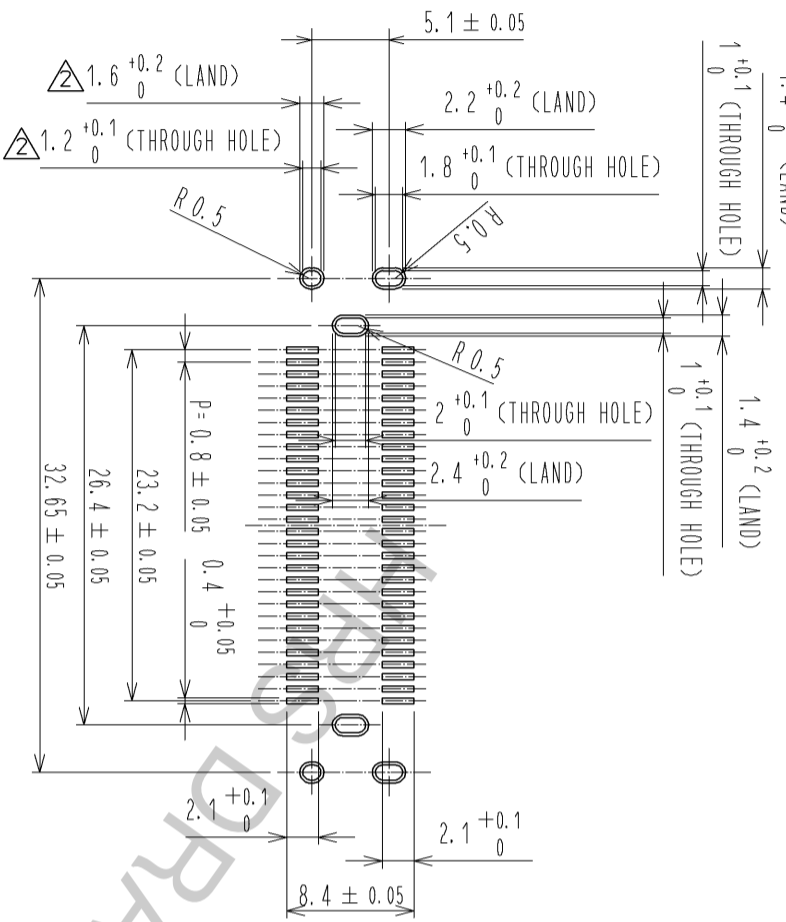
NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
1	POLYAMIDE	BLACK	UL94V-0	4	PHOSPHOR BRONZE	UNDER PLATING: NICKEL	1.3μm
2	PHOSPHOR BRONZE	LEAD AREA: GOLD	0.03μm	5	POLYSTYRENE		
3	PHOSPHOR BRONZE	CONTACT AREA: GOLD	0.1μm	6	POLYIMIDE		
		LEAD AREA: TIN-PLATING	1μm				
		UNDER PLATING: NICKEL	1.3μm				
		CONTACT AREA: GOLD	0.1μm				
		LEAD AREA: GOLD	0.1μm				
		UNDER PLATING: NICKEL	1.3μm				

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	TH. SANO	DESIGNED	CHECKED	DATE
mm	2:1	1	DIS-F-005993		KI. HIROKAWA	KI. HIROKAWA	12.01.27

APPROVED	CHECKED	DESIGNED	DRAWING
HS. OKAWA	HS. OKAWA	KI. HIROKAWA	EDC3-159561-00
			FX18-60P-0.85V
			CL579-0017-2-00



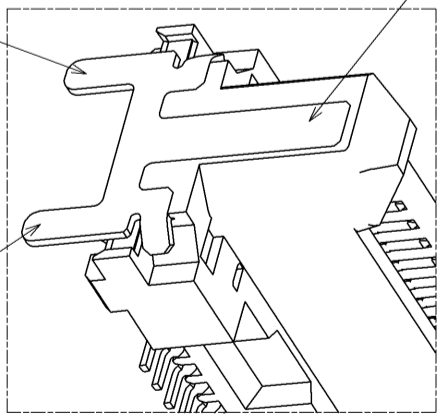
RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)
 (PCB THICKNESS: t=1.6mm METAL MASK THICKNESS: t=0.12mm)



5 DRAWING FOR PACKING(1:2)

8 CONFIGURATION OF MF CONTACT A

CONTACT AREA OF MF CONTACT A



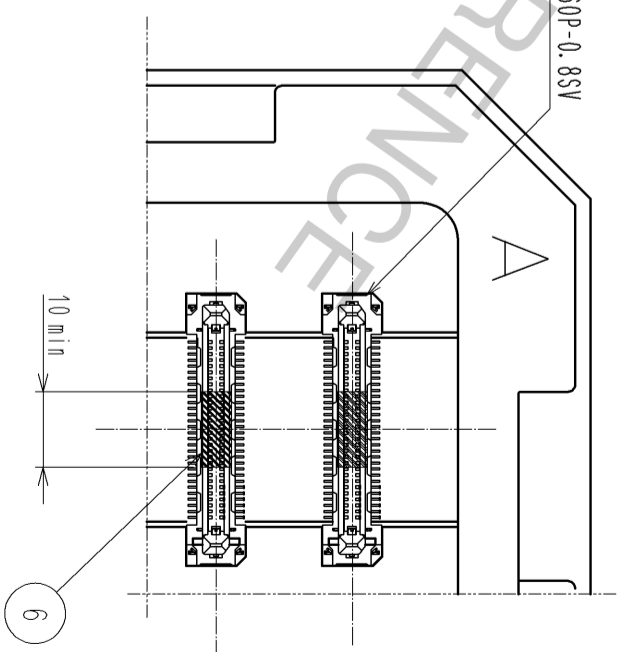
SOLDERING POLE2 OF MF CONTACT A

SOLDERING POLE1 OF MF CONTACT A

NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES. BE SURE TO CONNECT TO THE SAME CIRCUIT.

5

C(1:1)



6

HRS	
DRAWING NO.	EDC3-159561-00
PART NO.	FX18-60P-0.8SV
CODE NO.	CL579-0017-2-00